AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A method for manufacturing electron emitters by providing pairs of element electrodes, and conductive layers connecting the element electrodes to each other on a substrate, the method comprising:

a step of forming banks surrounding electrode-forming regions for forming the element electrodes and conductive-layer forming regions for forming the conductive layers;

a step of discharging first droplets toward the electrode-forming regions; and

a step of discharging second droplets toward the conductive-layer forming regions; and

a step of removing the banks.

- 2. (Original) The method of manufacturing electron emitters according to Claim 1, further comprising a step of lyophobing the banks.
- 3. (Original) The method of manufacturing electron emitters according to Claim 1, wherein the banks are formed using a lyophobic material.

- 4. (Original) The method for manufacturing electron emitters according to Claim 1, further comprising a step of lyophilizing at least one of the electrode-forming region and the conductive-layer forming region.
- 5. (Original) An electron emitter manufactured by the method according to Claim 1.
 - 6. 8. (Cancelled)
- 9. (Currently Amended) A method for manufacturing an electron emitter comprising:

defining a pair of spaced apart electrode-forming regions on a substrate;

defining a conductive layer-forming region on the substrate, the conductive layerforming region interconnecting the electrode-forming regions;

forming a bank encircling the electrode-forming regions and the conductive layerforming region;

discharging first droplets toward the electrode-forming regions to form a pair of element electrodes; and

discharging second droplets toward the conductive layer-forming regions to form a conductive layer connecting the element electrodes to each other; and

removing the bank after the conductive layer and element electrodes are formed.

- 10. (Previously Presnted) The method of claim 9, further comprising treating a portion of the conductive layer to form an electron-emitting section.
 - 11. (Cancelled)
- 12. (Previously Presented) The method of claim 9 further comprising rendering the bank lyophobic.
- 13. (Previously Presented) The method of claim 9 further comprising rendering at least one of:

the electrode-forming regions; and

the conductive layer-forming region;

lyophilic.

14. (new) A method for manufacturing electron emitters by providing pairs of element electrodes, and conductive layers connecting the element electrodes to each other on a substrate, the method comprising:

a step of forming banks surrounding electrode-forming regions for forming the element electrodes and conductive-layer forming regions for forming the conductive layers;

a step of discharging first droplets toward the electrode-forming regions; and a step of discharging second droplets toward the conductive-layer forming regions; and

a step of lyophobing the banks.

- 15. (new) The method of manufacturing electron emitters according to Claim 14, wherein the banks are formed using a lyophobic material.
- 16. (new) The method for manufacturing electron emitters according to Claim 1, further comprising a step of lyophilizing at least one of the electrode-forming region and the conductive-layer forming region.
- 17. (New) An electron emitter manufactured by the method according to Claim 14.